

**NP043A2**

Silicon NPN epitaxial planar type (Tr1)  
Silicon PNP epitaxial planar type (Tr2)

For digital circuits

## ■ Features

- SSS-Mini type 6-pin package, reduction of the mounting area and assembly cost by one half
- Maximum package height (0.4 mm) contributes to develop thinner equipments

## ■ Basic Part Number

- UNR31A2 + UNR32A2

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

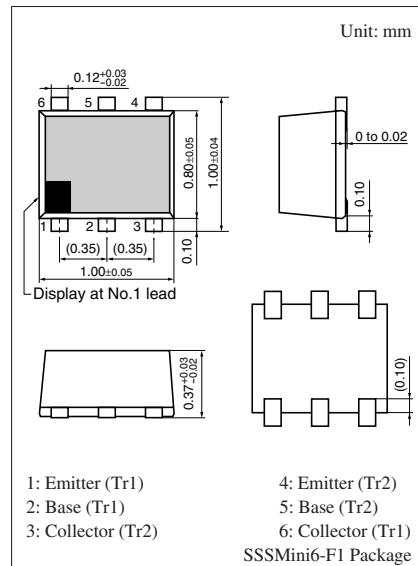
Parameter		Symbol	Rating	Unit
Tr1	Collector-base voltage (Emitter open)	$V_{CBO}$	50	V
	Collector-emitter voltage (Base open)	$V_{CEO}$	50	V
	Collector current	$I_C$	80	mA
Tr2	Collector-base voltage (Emitter open)	$V_{CBO}$	-50	V
	Collector-emitter voltage (Base open)	$V_{CEO}$	-50	V
	Collector current	$I_C$	-80	mA
Overall	Total power dissipation	$P_T$	125	mW
	Junction temperature	$T_j$	125	°C
	Storage temperature	$T_{stg}$	-55 to +125	°C

## ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

• Tr1

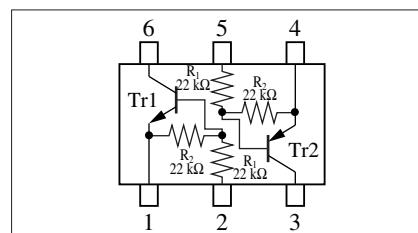
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_C = 10 \mu A, I_E = 0$	50			V
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = 2 mA, I_B = 0$	50			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 50 V, I_E = 0$			0.1	$\mu A$
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = 50 V, I_B = 0$			0.5	$\mu A$
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = 6 V, I_C = 0$			0.2	mA
Forward current transfer ratio	$h_{FE}$	$V_{CE} = 10 V, I_C = 5 mA$	60			—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 10 mA, I_B = 0.3 mA$			0.25	V
Output voltage high level	$V_{OH}$	$V_{CC} = 5 V, V_B = 0.5 V, R_L = 1 k\Omega$	4.9			V
Output voltage low level	$V_{OL}$	$V_{CC} = 5 V, V_B = 2.5 V, R_L = 1 k\Omega$			0.2	V
Input resistance	$R_I$		-30%	22	+30%	$k\Omega$
Resistance ratio	$R_I / R_2$		0.8	1.0	1.2	—
Transition frequency	$f_T$	$V_{CB} = 10 V, I_E = -1 mA, f = 200 MHz$		150		MHz

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.



Marking Symbol: 7T

## Internal Connection



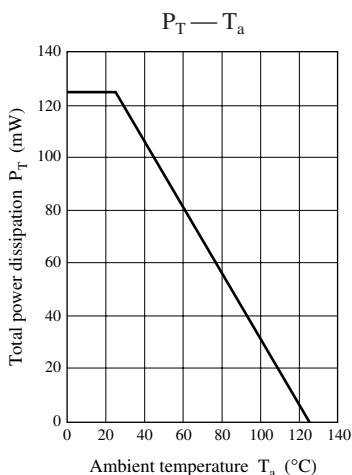
■ Electrical Characteristics (continued)  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$ 

- Tr2

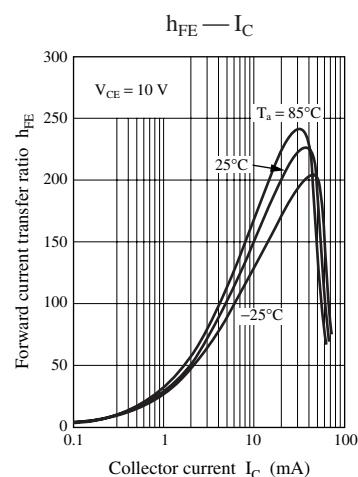
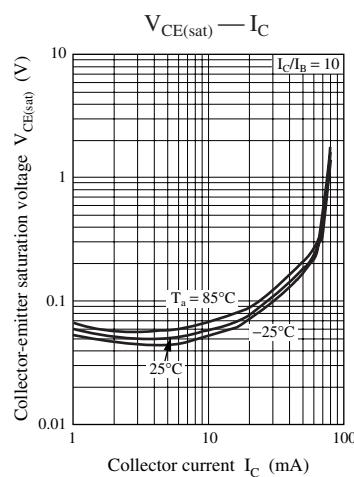
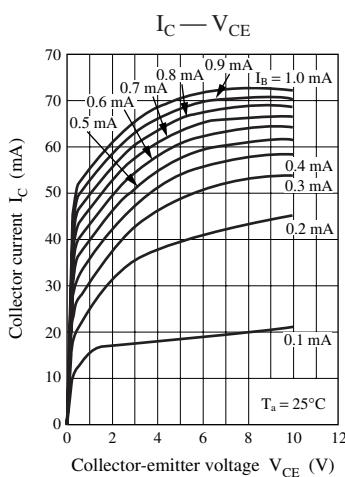
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_C = -10 \mu\text{A}, I_E = 0$	-50			V
Collector-emitter voltage (Base open)	$V_{CEO}$	$I_C = -2 \text{ mA}, I_B = 0$	-50			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = -50 \text{ V}, I_E = 0$			-0.1	$\mu\text{A}$
Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = -50 \text{ V}, I_B = 0$			-0.5	$\mu\text{A}$
Emitter-base cutoff current (Collector open)	$I_{EBO}$	$V_{EB} = -6 \text{ V}, I_C = 0$			-0.2	mA
Forward current transfer ratio	$h_{FE}$	$V_{CE} = -10 \text{ V}, I_C = -5 \text{ mA}$	60			—
Collector-emitter saturation voltage	$V_{CE(\text{sat})}$	$I_C = -10 \text{ mA}, I_B = -0.3 \text{ mA}$			-0.25	V
Output voltage high level	$V_{OH}$	$V_{CC} = -5 \text{ V}, V_B = -0.5 \text{ V}, R_L = 1 \text{ k}\Omega$	-4.9			V
Output voltage low level	$V_{OL}$	$V_{CC} = -5 \text{ V}, V_B = -2.5 \text{ V}, R_L = 1 \text{ k}\Omega$			-0.2	V
Input resistance	$R_I$		-30%	22	+30%	$\text{k}\Omega$
Resistance ratio	$R_I / R_2$		0.8	1.0	1.2	—
Transition frequency	$f_T$	$V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$		80		MHz

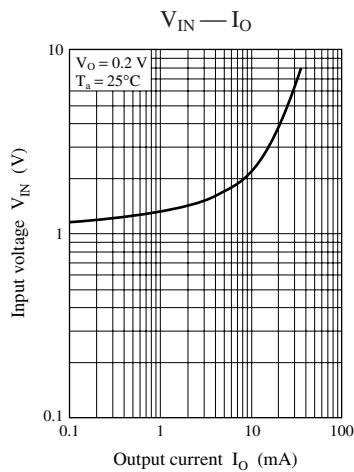
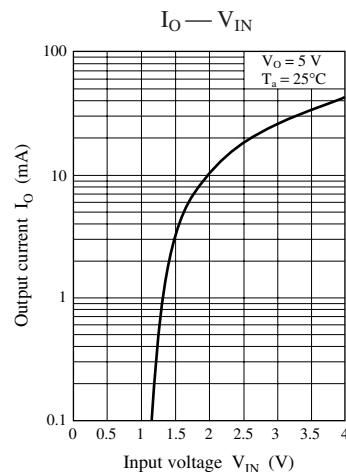
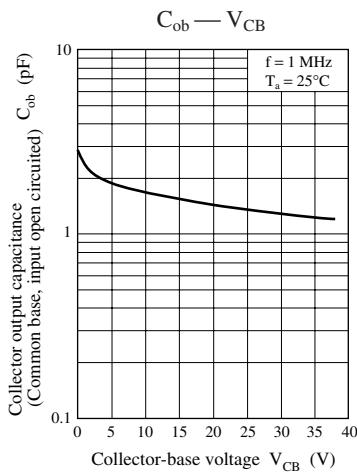
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

## Common characteristics chart

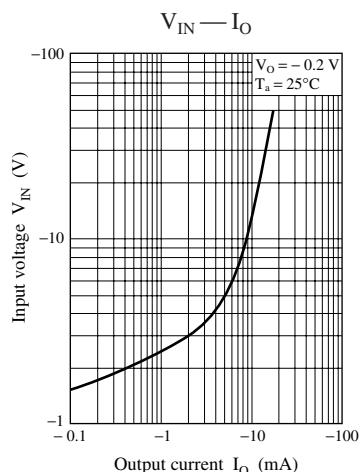
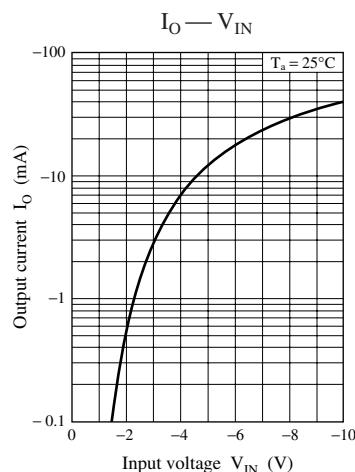
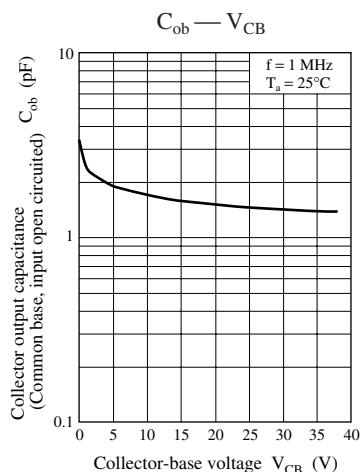
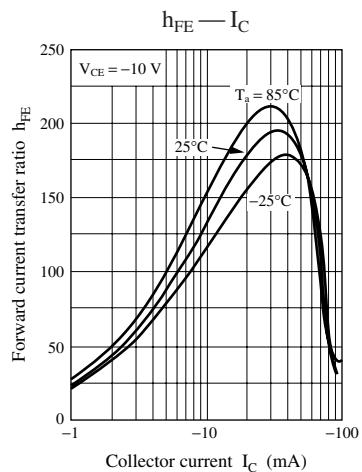
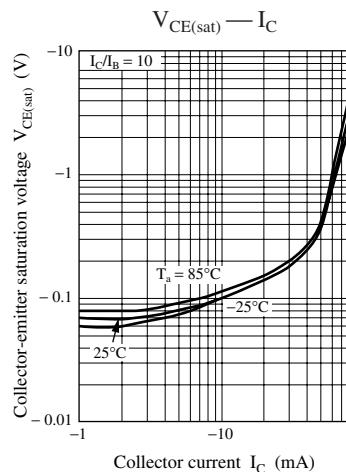
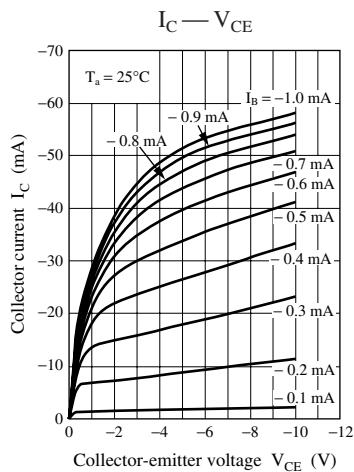


## Characteristics charts of Tr1





Characteristics charts of Tr2



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